

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1506	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 08:39
L2	1472	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4) and (liquid near4 resin) and foam and ultraviolet and probe	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 08:55
L3	1472	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4) and (liquid near4 resin) and foam and ultraviolet and probe and acid and viscosity and (plate near4 (glass or plastic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 08:58
L4	1472	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4) and (liquid near4 resin) and foam and ultraviolet and probe and acid and viscosity and (plate near4 (glass or plastic)) and 438/460.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 09:00

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L5	1472	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4) and (liquid near4 resin) and foam and ultraviolet and probe and acid and viscosity and (plate near4 (glass or plastic)) and (438/460-465.ccls. )	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 09:01
L6	1	(substrate or semiconductor or wafer or carrier) and street\$2 and circuit and (support or hold\$4) and (adhes\$5 or epoxy or resin) and grind\$4 and (chuck near4 table)and tap\$4 and bond\$4 and (dic\$4 or cut\$4) and ("light transmissive" or mirror) and chip and groove and (bak\$4 or heat\$4 or thermal or anneal or radiat\$4) and (liquid near4 resin) and foam and ultraviolet and probe and acid and viscosity and (plate near4 (glass or plastic)) and frame and (438/460-465.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 09:13
S1	1	(substrate or semiconductor or wafer) and (support or plat\$4) and grind\$4 and tap\$4 and bond\$4 and dic\$4 and chuck and "light transmissive" and chip and groove and radiat\$4 and resin and foam and liquid and viscosity and probe and (glass or plastic) and (bak\$4 or heat\$4 or thermal or anneal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 08:21
S2	1	(substrate or semiconductor or wafer) and (support or plat\$4) and grind\$4 and tap\$4 and bond\$4 and dic\$4 and chuck and "light transmissive" and chip and groove and radiat\$4 and resin and foam and liquid and viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 07:46

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S3	16	(substrate or semiconductor or wafer) and (support or plat\$3) and grind\$4 and tap\$4 and bond\$4 and dic\$4 and chuck and mirror and chip and groove and radiat\$4 and resin and foam and liquid and viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/21 07:48
S4	1	grind\$4 and (prob\$2 or sensor\$2) and measur\$4 and (semiconductor or wafer or substrate) and resin and "quinone-diazido"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:52
S5	34	"quinone-diazido"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:52
S6	1	"quinone-diazido" and resin and (ultraviolet near4 radiation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:53
S7	3	"quinone-diazido" and resin and ultraviolet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:54
S8	2	"quinone-diazido" and resin and ultraviolet and radiat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:53
S9	2	"quinone-diazido" and resin and ultraviolet and acid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:55
S10	1	"quinone-diazido" and resin and ultraviolet and acid and (acryl or urethane or polyester or "novolac phenol")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:56

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S11	1	"quinone-diazido" and resin and ultraviolet and acid and acryl	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:56
S12	3	"quinone-diazido" and resin and acid and (acryl or urethane or polyester or "novolac phenol")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 11:57
S13	1	"quinone-diazido" and resin and acid and (acryl or urethane or polyester or "novolac phenol") and viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:36
S14	4	"quinone-diazido" and resin and viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:37
S15	49	quinonediazido and resin and viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:37
S16	2	quinonediazido and resin and viscosity and (spin near4 coat)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:38
S17	2	quinonediazido and resin and viscosity and (spin near4 coat) and (bak\$4 or heat\$4 or thermal\$4 or anneal\$4 or temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:39
S18	2	quinonediazido and resin and viscosity and (spin near4 coat) and (bak\$4 or heat\$4 or thermal\$4 or anneal\$4 or temperature) and time	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 13:39